I am writing to express my keen interest in a summer internship in Thermal Engineering. I am a junior mechanical engineer at Lehigh University with real-world working experience looking for an opportunity to build on that experience with an internship with IBM.

Last summer I had a tremendous opportunity to work for Alcatel-Lucent in Bell Labs, which provided me with invaluable insight into the engineering industry, as well as some common thermal systems. My objectives were to do thermal and acoustic analysis of key 4G LTE and eventual 5G Base Band Units (BBUs). Because of the amount of heat being generated by the 5G components, special considerations had to be made to keep the components within operating temperature within even the harshest external environments.

This experience, coupled with my competitive education, makes me a candidate uniquely poised to excel with a position at IBM. During my experience at Lehigh, I believe I have developed many of the key skills required to excel at this position. For example one project involved design and casting of a heat sink, as well as LABVIEW testing to determine performance. Yet another was to design a helical heat exchanger to heat pharmaceutical to critical temperature.

I welcome an opportunity to meet and discuss my qualifications and candidacy in greater detail. In the interim, I thank you for your attention and forthcoming response.